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10/615,067	07/09/2003	Toshifumi Kojima	040894-5940	7994
9629 7590 09/06/2007 MORGAN LEWIS & BOCKIUS LLP 1111 PENNSYLVANIA AVENUE NW			EXAMINER	
			LAM, CATHY	LAM, CATHY FONG FONG
WASHINGTON, DC 20004			ART UNIT	PAPER NUMBER
			1775	
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Please find below and/or attached an Office communication concerning this application or proceeding.

The time period for reply, if any, is set in the attached communication.

	Application No.	Applicant(s)
	10/615,067	KOJIMA ET AL.
Office Action Summary	Examiner	Art Unit
	Cathy Lam	1775
The MAILING DATE of this communication app Period for Reply	pears on the cover sheet with the c	orrespondence address
A SHORTENED STATUTORY PERIOD FOR REPLY WHICHEVER IS LONGER, FROM THE MAILING DATE of the state of the provisions of 37 CFR 1.13 after SIX (6) MONTHS from the mailing date of this communication. If NO period for reply is specified above, the maximum statutory period was a failure to reply within the set or extended period for reply will, by statute, Any reply received by the Office later than three months after the mailing earned patent term adjustment. See 37 CFR 1.704(b).	ATE OF THIS COMMUNICATION 36(a). In no event, however, may a reply be time will apply and will expire SIX (6) MONTHS from , cause the application to become ABANDONE	N. nely filed the mailing date of this communication. D (35 U.S.C. § 133).
Status		•
Responsive to communication(s) filed on <u>07 Jules</u> This action is FINAL . 2b) ☐ This Since this application is in condition for allower closed in accordance with the practice under E	action is non-final.	
Disposition of Claims		·
4) Claim(s) 5-7 and 11-17 is/are pending in the ap 4a) Of the above claim(s) is/are withdraw 5) Claim(s) is/are allowed. 6) Claim(s) 5-7 and 11-17 is/are rejected. 7) Claim(s) is/are objected to. 8) Claim(s) are subject to restriction and/or Application Papers 9) The specification is objected to by the Examine 10) The drawing(s) filed on is/are: a) access applicant may not request that any objection to the of Replacement drawing sheet(s) including the correct 11) The oath or declaration is objected to by the Examine	wn from consideration. r election requirement. r. epted or b) □ objected to by the Edrawing(s) be held in abeyance. See ion is required if the drawing(s) is objected.	e 37 CFR 1.85(a). jected to. See 37 CFR 1.121(d).
Priority under 35 U.S.C. § 119		
12) Acknowledgment is made of a claim for foreign a) All b) Some * c) None of: 1. Certified copies of the priority documents 2. Certified copies of the priority documents 3. Copies of the certified copies of the prior application from the International Bureau * See the attached detailed Office action for a list of	s have been received. s have been received in Application rity documents have been receive u (PCT Rule 17.2(a)).	on No ed in this National Stage
Attachment(s) 1) Notice of References Cited (PTO-892) 2) Notice of Draftsperson's Patent Drawing Review (PTO-948) 3) Information Disclosure Statement(s) (PTO/SB/08) Paper No(s)/Mail Date	4) Interview Summary Paper No(s)/Mail Da 5) Notice of Informal Pa	ite

Application/Control Number: 10/615,067

Art Unit: 1775

In view of the amendment and remarks filed on June 07, 2007, the pending claims continue to be unpatentable as following:

Claim Rejections - 35 USC § 102

1. Claims 5-6 and 17 are rejected under 35 U.S.C. 102(e) as being clearly anticipated by Yamamoto et al (US 6916873).

Yamamoto discloses a liquid thermosetting resin composition that is used for filling via holes and/or through holes in printed wiring boards (col 1 L 14-18).

The printed wiring boards comprise insulating layers, via holes and/or through holes, and conductive circuit patterns (col 1 L 39-45). The via holes and/or through holes are formed in the thickness of the insulating layers and plated with copper. The thermosetting resin composition is used to fill the via holes for providing conductive connection between the conductive circuit patterns (col 10 L 55-60 & Figs. 1(a)-1(g)).

The liquid thermosetting resin composition is comprised of (A) an epoxy resin,
(B) a curing catalyst, (C) a filler and (D) a coupling agent (col 2 L 63-65 & col 3 L 6-8).

The curing catalyst (B) can be dicyandiamide (col 6 L 64 & col 7 L 17-18). The filler (C) are inorganic fillers which can either be conductive or non-conductive particles (col 8 L 10-16). Depending on the type of fillers used, the average filler size is 1-2 μ m for spherical fine filler and 4-10 μ m for ground filler (col 7 L 64-col 8 L 4).

The coupling agent (D) can be a silane coupling agent which comprises an urea end group (col 9 L 6-11).

The prior art is silent about the dicyandiamide is for reducing deterioration in adhesive strength between the resin composition and the conductor layer. Since

Application/Control Number: 10/615,067

Art Unit: 1775

Yamamoto teaches the same dicyandiamide as the present invention, it would be inherent that Yamamoto's dicyandiamide curing catalyst possesses the same function.

Claim Rejections - 35 USC § 103

2. Claims 7, 11-16 are rejected under 35 U.S.C. 103(a) as being unpatentable over Yamamoto et al (US 6916873).

Yamamoto teaches the present invention but is silent about the size of the via hole or through hole, the dicyandiamide is in powder format and the specific type of urea compound used.

In view of Yamamoto's teaching, one skill in the art would choose a desired via hole size because choosing a workable size is just a matter of design choice.

Regarding top the dicyandiamide curing agent in powders, dendrites or flakes format, since applicant has not stated any advantages of using such, the examiner is taking the position that the prior art (even in different physical format) would perform the same job.

Regarding to the specific type of urea compound, the examiner is taking the position that one skill in the art would choose the claimed urea compounds because finding a workable material involves only routine experimentations.

Response to Arguments

3. Applicant's arguments filed on June 07, 2007 have been fully considered but they are not persuasive. Applicant in the remarks traverses the art rejections and raises the following issues:

Application/Control Number: 10/615,067

Art Unit: 1775

A. The silane coupling agent of Yamamoto does not correspond to the claimed curing catalyst. In contrast, the present invention is directed to the filler particles may be subjected to surface treatment with a silane coupling agent.

B. The silane coupling agent is a liquid, whereas the claimed curing catalyst is used to cured the resin and urea is powder.

In respond to the above issues:

- A. The silane coupling agent in Yamamoto was NOT used as a curing catalyst. The silane coupling agent was used to enhance the wettability of the filler in the liquid thermosetting resin (col 5 L 34-41). The coupling agent can either be added into the liquid composition or onto the surface of the filler as surface pretreatment (col 8 L 58-62).
- B. The silane coupling agent disclosed in Yamamoto are organic compound, it improves the wettability of the filler and decreases the viscosity of the thermosetting resin composition (col 9 L 6-14 & col 5 L 36-41). Clearly, the silane coupling agent is a liquid. There is no clear description in the specification that the urea is a powder.

In respond to applicant's issues, Yamamoto continues to anticipate and/or obvious over the present invention. Thus, the art rejections sustain.

Conclusion

4. THIS ACTION IS MADE FINAL. Applicant is reminded of the extension of time policy as set forth in 37 CFR 1.136(a).

A shortened statutory period for reply to this final action is set to expire THREE MONTHS from the mailing date of this action. In the event a first reply is filed within

Art Unit: 1775

TWO MONTHS of the mailing date of this final action and the advisory action is not mailed until after the end of the THREE-MONTH shortened statutory period, then the shortened statutory period will expire on the date the advisory action is mailed, and any extension fee pursuant to 37 CFR 1.136(a) will be calculated from the mailing date of the advisory action. In no event, however, will the statutory period for reply expire later than SIX MONTHS from the mailing date of this final action.

Primary Examiner

Art Unit 1775

cfl August 30, 2007